

## **BGA rework equipment --- Solder ball placement system BU-550E**

- (1) ■ Outside dimension: 75cm(L), 25cm(W), 26cm(H).**
- (2) ■ Weight: 30.2 kg.**
- (3) ■ Working voltage: 110/220V;50/60Hz**
- (4) ■ Working air pressure: 6 kg/cm<sup>2</sup>.**
- (5) ■ Solder ball specification: According to the solder ball spec being used by different kinds of BGA package.**
- (6) ■ BGA IC holder: It is available for changing-over different types of BGA IC holders according to different size or spec of BGA package.**
- (7) ■ Solder ball screening fixture: It is available for changing-over different ball screening fixtures according to different size or spec of solder ball.**
- (8) ■ Solder ball placing speed: The speed for placing solder balls onto BGA pads can be adjusted and fine-tuning controlled.**
- (9) ■ Ball-placing yield rate: 98%.**
- (10) ■ Ball-placing accuracy: 0.03mm.**
- (11) ■ BGA IC holder unloading speed: Unloading speed 30~300 mm/s.**
- (12) ■ Automatic ball-placing operation cycle time : 22 seconds.**

### ***BGA regeneration!***

**~ Place solder balls on BGA to regenerate a whole new one with the lowest cost. ~**

**The solder ball placement system places new solder balls again onto ball removed BGA-IC for new reflowing rework. This equipment provides a technology promotion for traditional BGA operation in SMT industry. It is a very useful tool for BGA production.**

**[There are patents approved by lots of countries for this equipment. All rights are reserved]**